

Title (en)

MICRO-FABRICATED GROUP ELECTROPLATING TECHNIQUE

Title (de)

GALVANISIERUNGSTECHNIK FÜR MIKROGEFERTIGTE GRUPPE

Title (fr)

TECHNIQUE D'ÉLECTROPLACAGE DE GROUPE MICRO-FABRIQUÉ

Publication

EP 3047709 A4 20170920 (EN)

Application

EP 14845731 A 20140912

Priority

- US 201361878992 P 20130917
- US 2014055474 W 20140912

Abstract (en)

[origin: WO2015041953A1] Methods, and devices produced by the methods, for electroplating a multitude of micro-scale electrodes that are electrically isolated from each other on a cable or other device is described. A localized area of connections on another end of the cable is shorted together by depositing a metal sheet or other conductive material over the localized area. The metal sheet is connected to a terminal of a power supply, and the electrode end of the cable is immersed in an electrolyte solution for electrodeposition by electroplating. After the electrodes are electroplated, the metal sheet is removed from the cable in order to re-isolate the electrodes.

IPC 8 full level

H05K 3/24 (2006.01); **A61N 1/05** (2006.01); **C23C 14/14** (2006.01); **C23C 14/24** (2006.01); **C25D 1/04** (2006.01); **H05K 1/18** (2006.01);
H05K 3/28 (2006.01); **H05K 3/32** (2006.01); **H05K 3/40** (2006.01)

CPC (source: EP US)

A61N 1/0543 (2013.01 - EP US); **C23C 14/14** (2013.01 - US); **C23C 14/24** (2013.01 - US); **C25D 1/04** (2013.01 - EP US);
H05K 3/064 (2013.01 - US); **H05K 3/242** (2013.01 - EP US); **H05K 1/189** (2013.01 - EP US); **H05K 3/244** (2013.01 - EP US);
H05K 3/28 (2013.01 - EP US); **H05K 3/321** (2013.01 - EP US); **H05K 3/4007** (2013.01 - EP US); **H05K 2203/0191** (2013.01 - EP US);
H05K 2203/0361 (2013.01 - EP US); **H05K 2203/0723** (2013.01 - EP US); **H05K 2203/1338** (2013.01 - EP US)

Citation (search report)

- [Y] EP 0110114 A1 19840613 - GRAH KLAUS
- [Y] EP 1289352 A2 20030305 - HITACHI LTD [JP], et al
- [Y] US 2007120235 A1 20070531 - SHIMOISHIZAKA NOZOMI [JP], et al
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Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

WO 2015041953 A1 20150326; CN 105432156 A 20160323; CN 105432156 B 20180918; CN 105432156 B8 20181109;
EP 3047709 A1 20160727; EP 3047709 A4 20170920; EP 3047709 B1 20200715; US 10617011 B2 20200407; US 2016105973 A1 20160414

DOCDB simple family (application)

US 2014055474 W 20140912; CN 201480041315 A 20140912; EP 14845731 A 20140912; US 201514974404 A 20151218